



Attorney Docket No. 9180-10CT

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Glenn A. Rinne et al;  
Application No.: 10/790,967  
Filed: March 2, 2004  
For: LOW TEMPERATURE METHODS OF BONDING COMPONENTS AND  
RELATED STRUCTURES

Group Art Unit: 1725  
Examiner: Michael Aboagye

Date: February 1, 2006

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT  
PURSUANT TO 37 C.F.R. §1.97(c)

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(c), before final Office Action or Allowance, whichever is earlier.

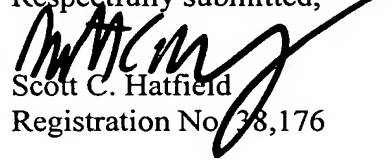
In accordance with the requirements of 37 C.F.R. § 1.97(c)(1), the following Certification as specified in 37 C.F.R. § 1.97(e) is made:

In accordance with the requirements of 37 C.F.R. § 1.97(c)(2), the Commissioner is authorized to charge the \$180.00 fee specified in 37 C.F.R. § 1.17(p) and any deficiency or credit any overpayment to Deposit Account No. 50-0220.

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Application No.: 10/790,967  
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It is requested that these documents be considered by the Examiner and  
officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and  
Section 609 of the MPEP.

Respectfully submitted,



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**INFORMATION DISCLOSURE  
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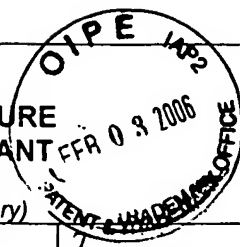
(use as many sheets as necessary)

Sheet

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of

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**Complete if Known**

Application Number	10/790,967
Filing Date	March 2, 2004
First Named Inventor	Glenn A. Rinne
Group Art Unit	1725
Examiner Name	Michael Aboagye
Attorney Docket Number	9180-10CT

**U.S. PATENTS AND PATENT PUBLICATIONS**

Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
	1.	US-2001/0011764		Elenius et al.	08/2001
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Examiner Signature

Date Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				<b>Complete if Known</b>	
				Application Number	10/790,967
				Filing Date	March 2, 2004
				First Named Inventor	Glenn A. Rinne
				Group Art Unit	1725
Examiner Name	Michael Aboagye				
Attorney Docket Number	9180-10CT				
Sheet	2	of	7		

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	50.	US-4,640,438	Trevison et al;	02/1987
	51.	US-4,473,263	Sunstein	09/1984
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	55.	US-4,545,610	Lakritz et al;	10/1985
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Examiner Signature		Date Considered	
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Substitute form 1449A/PTO				<b>Complete if Known</b>	
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				Group Art Unit	1725
				Examiner Name	Michael Aboagye
(use as many sheets as necessary)				Attorney Docket Number	9180-10CT
Sheet	3	of	7		

	102.	US-5,251,806		Agarwala et al.	10/12/1993
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	104.	US-5,293,006		Yung	03/1994
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	154.	US-6,027,957		Merritt et al.	02/2000

Examiner Signature		Date Considered	
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				Group Art Unit	1725
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Sheet	4	of	7		

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Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	T	
		Office	Number	Kind Code (if known)				
	195.	CN	1269607		English Abstract	01/03/2002		
	196.	DE	42 05 029 C		Germany	02/1993	Abstract	
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Examiner Signature		Date Considered	
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				Group Art Unit	1725
				Examiner Name	Michael Aboagye
(use as many sheets as necessary)				Attorney Docket Number	9180-10CT
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	201.	EP	1 148 548		Advanced Interconnect Technology, Ltd.	10-24-2001	
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	227.	JP	2000349111		Fujitsu, Ltd.	12-15-2000	Abstract
	228.	JP	2002203868		Toshiba Corp	07-19-2002	Abstract
	229.	WO	02/03461		Intel Corporation	01/10/2002	
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OTHER NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
	236.	Adema et al., <i>Flip Chip Technology: A Method for Providing Known Good Die with High Density Interconnections</i> , MCM '94 Proceedings, pp. 41-49.	
	237.	Arai et al. "Sn-Ag Solder Bump Formation for Flip-Chip Bonding by Electroplating" <i>Journal of the Electrochemical Society</i> 150(10): c730-c734 (2003)	
	238.	Audet, et al; <i>Low Cost Bumping Process for Flip Chip</i> , Proc. 1995 International Flip Chip, BGA, and Ado Pkg. Symposium ITAP 95, '95 Flip Chip, BGA, TAB & AP Symposium, pp 16-21 (1995).	
	239.	Chan "Investigation of Cr/Cu/Cu/Ni Under Bump Metallization for Lead-free Applications" <i>2002 Electronics Packaging Technology Conference</i> 270-275 (2002)	
	240.	Choi et al; <i>Electromigration of Flip Chip Solder Bump on Cu/Ni(V) A1 Thin Film Under Bump Metallization</i> ; 2002 Electronic Components and Technology Conference; pp 1201-1205.	
	241.	Datta, et al., <i>Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections</i> , J. Electrochem. Soc., vol 142, No. 11, pp 3779-3785 (Nov. 1995).	
Examiner Signature		Date Considered	

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			Filing Date	March 2, 2004
			First Named Inventor	Glenn A. Rinne
			Group Art Unit	1725
			Examiner Name	Michael Aboagye
			Attorney Docket Number	9180-10CT
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Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



Substitute form 1449/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				<b>Complete if Known</b>	
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